CLAIMS:

1. A printed circuit board comprising:

a substrate;

a conductor pattern formed on the substrate; and

a protection film coating the substrate and the conductor pattern, wherein the conductor pattern includes a bottom surface contacting the substrate, a top surface opposite to the bottom surface, and a pair of side surfaces, each of the side surfaces having a lower side surface covered by the protection film and an upper side surface exposed from the protection film, and the width of the bottom surface being greater than the width of the top surface.

2. The printed circuit board according to claim 1, wherein the conductor pattern has a trapezoidal cross-section that is perpendicular to the longitudinal direction of the conductor pattern.

3. The printed circuit board according to claim 1, wherein the pair of side surfaces are concave surfaces.

4. The printed circuit board according to claim 1, wherein the height of the portion coated by the protection film in the conductor pattern is 50% or greater and less than 100% of the height of the conductor pattern.

5. The printed circuit board according to claim 1, wherein the top surface and the upper side surfaces are coated by a plating.

6. The printed circuit board according to claim 5,

further comprising a solder ball contacting the conductor pattern at the upper side surfaces.

7. The printed circuit board according to claim 1, wherein a value obtained by dividing one half of a value obtained by subtracting the width of the top surface from the width of the bottom surface by the height of the conductor pattern is in the range of 0.1 to 2.5.

8. A method for fabricating a printed circuit board comprising the steps of:

etching a substrate including a conductor to form a conductor pattern, wherein the conductor pattern is formed so that a width of a bottom surface contacting the substrate is greater than a width of a top surface, which is opposite the bottom surface;

applying an insulative protection film to the conductor pattern and the substrate; and

removing part of the protection film to expose an upper portion of the conductor pattern.

9. The fabrication method according to claim 8, further comprising the steps of:

plating the exposed upper portion of the conductor pattern; and

joining a solder ball to the plated upper portion of the conductor pattern.